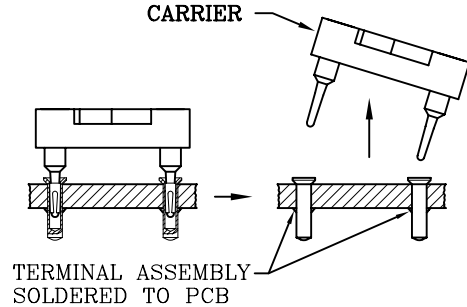


HI-RELIABILITY ULTRA LOW PROFILE CARRIER SOCKET ASSEMBLIES

- LOW PROFILE ABOVE PCB
- MAINTAINS ACCURATE PIN TO PIN LOCATION
- PREVENTS CONTACT CONTAMINATION DURING SOLDERING
- AVAILABLE IN PGA, DIP, AND SIP CONFIGURATIONS
- RIGID CARRIER EASES PIN INSERTION WITH STANDARD AUTO-INSERTION EQUIPMENT

TYPICAL APPLICATIONS



TECHNICAL SPECIFICATIONS

MATERIALS

CARRIER INSULATOR: GLASS FILLED POLYESTER
UL 94V-0
CARRIER TERMINAL: COPPER ALLOY, NICKEL PLATE

TERMINAL ASSEMBLY:

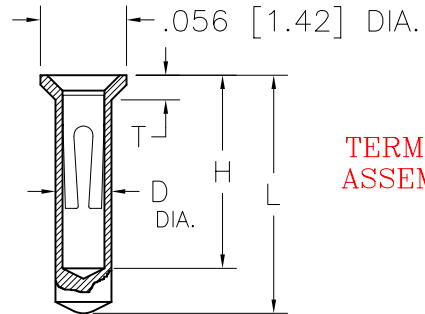
TERMINAL: BRASS, PER ASTM-B16
CONTACT: BeCu, PER ASTM-B194

CONTACT FORCE:

INSERTION FORCE: 2.8 oz. (MAX.)
WITHDRAWAL FORCE: 0.5 oz. (MIN.)
MOUNTING HOLE DIAMETER .039 [0.99] (MIN.)

PLATING

-P17 TERMINAL: TIN-LEAD
CONTACT: GOLD 30 μ INCH
-P29 TERMINAL: TIN-LEAD
CONTACT: GOLD 10 μ INCH
-P32 TERMINAL: TIN-LEAD
CONTACT: TIN 200 μ INCH



TERMINAL ASSEMBLY

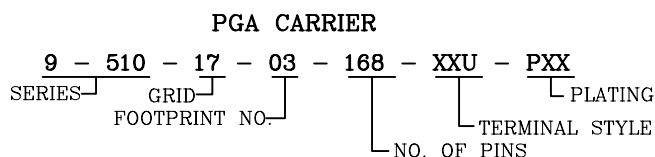
TYPE	H	L	D	T
-52U	.120[3.05]	.136[3.45]	.038[.97]	.016[.41]
-54U	.138[3.51]	.155[3.94]	.034[.86]	.031[.79]

* ALL DIMENSIONS ARE FOR REFERENCE ONLY

PGA DEVICE	ANDON P\N
INTEL™ 80386	9-510-14-21-132-XXU-PXX-S10
INTEL™ 80486	9-510-17-03-168-XXU-PXX-S10
INTEL OVERDRIVE READY™	9-510-19-09-238-XXU-PXX-S10
INTEL PENTIUM™	9-510-21-04-273-XXU-PXX-S10

* PENTIUM™ AND OVERDRIVE READY™ ARE TRADEMARKS OF INTEL CORP.
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ORDERING INFORMATION



* CONSULT FACTORY FOR AVAILABLE SOCKET AND TERMINAL OPTIONS

